**ABSTRACT**

**INTERCONNECTS WITH HARMONIZED STRESS AND METHODS FOR FABRICATING THE SAME**

Interconnects with harmonized stress and methods for fabricating the same. An interconnect comprises a substrate having a conductive member. A composite low-k dielectric layer interposed with at least one stress-harmonizing layer therein overlies the substrate. A conductive feature in the composite low-k dielectric layer passes through the at least one stress-harmonizing layer to electrically connect the conductive member.

**(FIG.1)**